

MCU Related Document list

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1. Introduction

In LAPIS Technology's MCU, some manuals are prepared for other than User's Manual. This document is a list of the documents related to MCU. Read them as necessary.

1.1 Applicable MCU Products

ML62Q2500/2700 group
ML62Q1000 series
ML620Q50x group

2. Related Document list

| | Document name | Description |
|---------------------------|--|---|
| CPU core | nX-U16/100 Core Instruction Manual | Description on the basic architecture and the each instruction of the nX-U16/100 Core. |
| Assembler | MACU8 Assembler Package User's Manual | Description on the method of operating the relocatable assembler, the linker, the librarian, and the object converter and also on the specifications of the assembler language. |
| C Compiler | CCU8 User's Manual | Description on the method of operating the compiler. |
| | CCU8 Programming Guide | Description on the method of programming. |
| | CCU8 Language Reference | Description on the language specifications. |
| Library | MULDIVU8LIB Multiplication and Division Library for U8/U16 Accelerator User's Manual | Description on the MULDIVU8LIB Multiplication and Division Library. |
| Development Support tools | DTU8 Debugger User's Manual | Description on the method of operating the debugger DTU8. |
| | LEXIDE-U16 User's Manual | Description on the integrated development environment LEXIDE-U16. |
| | EASE1000V2 User's Manual | Description on the on-chip debug emulator EASE1000V2. |
| | HTU8 User's Manual | Description on the ROM code data generation tool HTU8. |
| | Multiple Flash Writer MWU16 User's Manual | Description on the Multiple Flash Writer MWU16. |

3. Revision History

| Document No. | Issue date | Page | | Description |
|----------------------|------------|---------------|-------------|--|
| | | Previous Rev. | Update Rev. | |
| FEXL_MCU_RELDLIST-01 | 2020.01.24 | - | - | First Revision |
| FEXL_MCU_RELDLIST-02 | 2020.04.12 | 1 | 1 | Updated note. |
| | | 2 | 2 | Added applicable products Deleted IDEU8 |